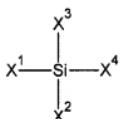


LISTING OF THE CLAIMS

A copy of the claims is included for the Examiner's convenience.

1. (Previously Presented) A method for producing an electrical device made up by a first object for bonding including a first electrode and a second object for bonding including a second electrode to be connected to said first electrode, by bonding said first object for bonding and said second object for bonding to each other, comprising the steps of
 - arranging an adhesive, mainly containing a thermosetting resin and a silane coupling agent as a first curing agent, at least on said first electrode, to form an adhesive layer, wherein electrically conductive particles are added to said adhesive from the outset;
 - arranging a second curing agent, reactive with said first curing agent by heating to polymerize said thermosetting resin, at least on said second electrode, to form a curing agent layer, said second curing agent being mainly composed of an aluminum chelate;
 - positioning said first and second electrodes in register with each other;
 - tightly contacting said adhesive layer on said first object for bonding with said curing agent layer on said second object for bonding; and
 - thrusting and heating said first and second objects against each other to soften said adhesive layer and mix said first and second curing agents for putting said electrically conductive particles between said first and second electrodes, and
 - further thrusting and heating said first and second objects to develop a cation by reaction of said silane coupling agent as a main component of said first curing agent and said aluminum chelate as a main component of the second curing agent to allow said thermosetting resin to be cationically polymerized.
2. (Cancelled)
3. (Cancelled)

4. (Previously Presented) The method for producing an electrical device according to claim 1 wherein said aluminum chelate is one of ethyl acetoacetate aluminum diisopropylate, alkyl acetoacetate aluminum diisopropylate and aluminum monoacetyl acetonate bis ethylacetoacetate.
5. (Previously Presented) The method for producing an electrical device according to claim 1 wherein a compound represented by the following formula:



is used as said silane coupling agent, wherein at least one of the substituents X^1 to X^4 is an alkoxy group and at least one of the substituents different from the alkoxy group includes an epoxy ring.

6. (Cancelled)
7. (Previously Presented) The method of producing an electrical device according to claim 1 wherein said thermosetting resin forming said adhesive layer is an epoxy resin and wherein said second curing agent layer further contains an epoxy resin.
8. (Previously Presented) The method of producing an electrical device according to claim 1 wherein said second curing layer is formed on said second electrode by spraying said second curing agent liquid at ambient temperature or a liquid dispersion containing said second curing agent dispersed therein.
9. (Cancelled)